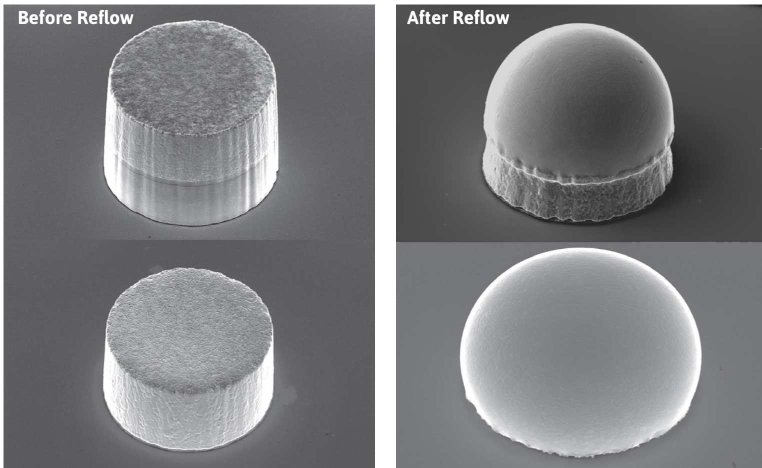
MICROFAB® TS-650

FOR THE MOST CRITICAL INTERFACE BETWEEN WLP AND SUBSTRATE

Introducing MICROFAB® TS-650: The premier tin-silver bump metallization from the market leader in copper pillar for FO-WLP



KEY FEATURES

- Foaming-free and stable electrolyte
- Environmentally-friendly lead-free process
- High deposition rates
- For bumping and capping applications
- Smooth and uniform deposit
- Tunable Ag composition
- Excellent post reflow WID bump uniformity
- Horizontal or vertical equipment

09:21
Self-Driving Mode
Waiting For Command...
P R N D 2 L
Power 1
Power 2
Energy1
Energy2
AUTO PARK

MacDermid Enthone

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